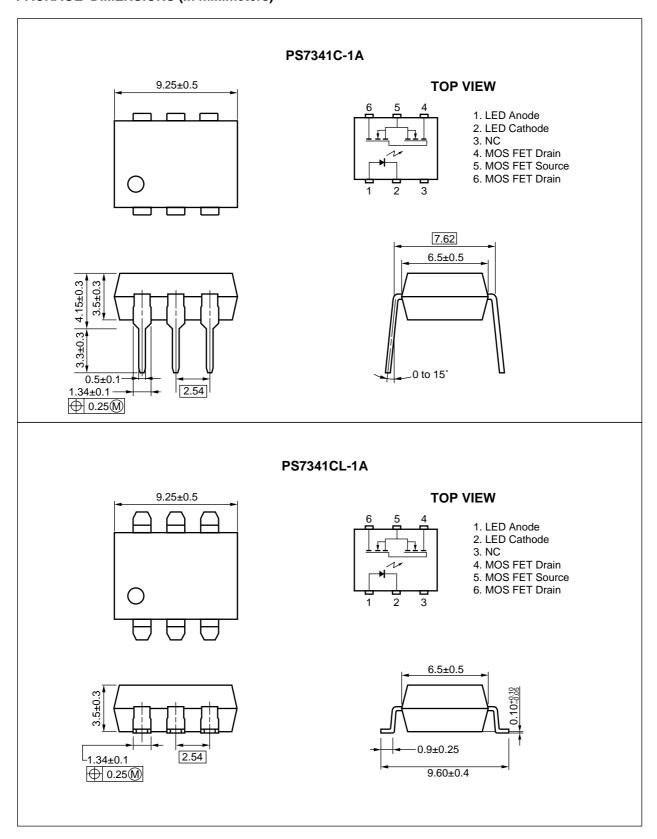
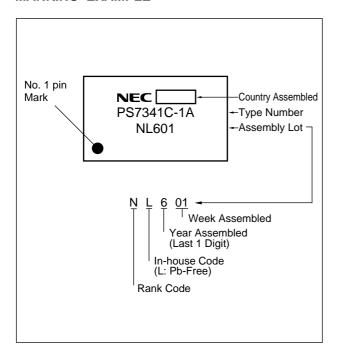
PACKAGE DIMENSIONS (in millimeters)



<R> MARKING EXAMPLE



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS7341C-1A	PS7341C-1A-A	Pb-Free	Magazine case 50 pcs	Standard products	PS7341C-1A
PS7341CL-1A	PS7341CL-1A-A			(UL, BSI, CSA, SEMKO,	
PS7341CL-1A-E3	PS7341CL-1A-E3-A		Embossed Tape 1 000 pcs/reel	DEMKO, NEMKO,	
PS7341CL-1A-E4	PS7341CL-1A-E4-A			FIMKO approved)	

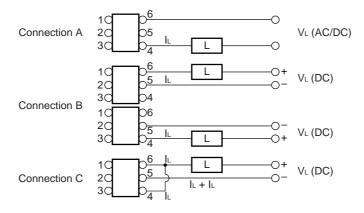
^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter			Symbol	Ratings	Unit	
Diode	Forward Current (De	C)	lF	50	mA	
	Reverse Voltage		VR	5.0	V	
	Power Dissipation		PD	50	mW	
	Peak Forward Curre	ent *1	I FP	1	Α	
MOS FET	Break Down Voltage		VL	400	V	
	Continuous	Connection A	lι	120	mA	
	Load Current*2	Connection B		120		
		Connection C		240		
	Pulse Load Current *3 (AC/DC Connection)		I LP	120	mA	
	Power Dissipation			560	mW	
Isolation Voltage*4			BV	3 750	Vr.m.s.	
Total Power Dissipation			Рт	610	mW	
Operating Ambient Temperature			TA	-40 to +85	°C	
Storage Temperature			Tstg	-40 to +125	°C	

^{*1} PW = 100 μ s, Duty Cycle = 1%

^{*2} Conditions: IF \geq 2 mA. The following types of load connections are available.



^{*3} PW = 100 ms, 1 shot

^{*4} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60% between input and output Pins 1-3 shorted together, 4-6 shorted together.

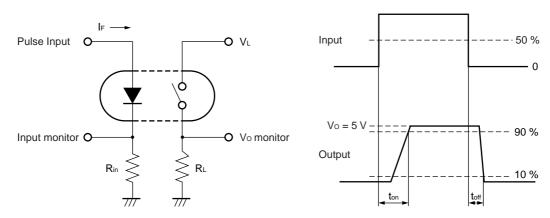
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lR	V _R = 5 V			5.0	μΑ
MOS FET	Off-state Leakage Current	Loff	V _D = 400 V		0.001	1.0	μА
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		63		pF
Coupled	LED On-state Current	I Fon	IL = 120 mA			2.0	mA
	On-state Resistance	Ron1	IF = 10 mA, IL = 10 mA		27	35	Ω
		Ron2	$I_F = 10 \text{ mA}, I_L = 120 \text{ mA}, t \le 10 \text{ ms}$		22	30	
	Turn-on Time *1, 2	ton	If = 10 mA, Vo = 5 V, R _L = 2 k Ω ,		0.55	1.0	ms
	Turn-off Time *1, 2	toff	PW ≥ 10 ms		0.07	1.0	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ⁹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		1.1		pF
	Limit Current *3	Іьмт	I _F = 10 mA, t = 5 ms, V _L = 6 V	125	200	250	mA

*1 Test Circuit for Switching Time



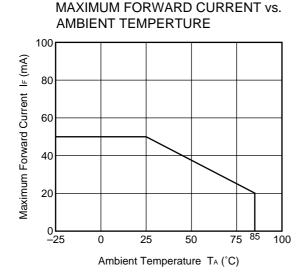
*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

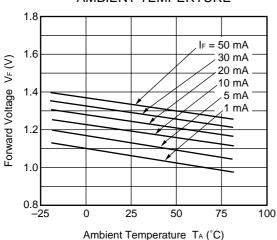
*3 N rank: 125 to 250 mA M rank: 125 to 180 mA L rank: 170 to 250 mA

<R>

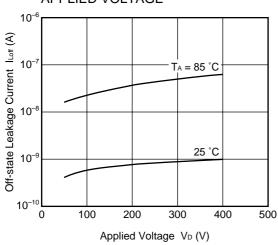
TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)



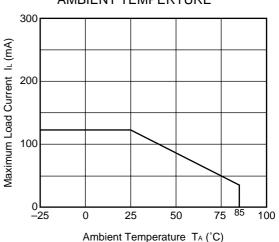




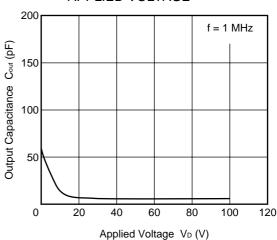
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



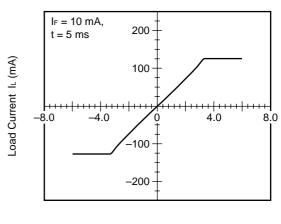
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERTURE



OUTPUT CAPACITANCE vs. APPLIED VOLTAGE

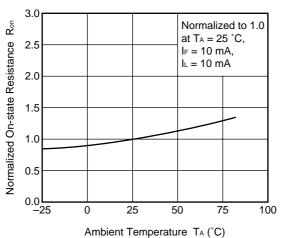


LOAD CURRENT vs. LOAD VOLTAGE

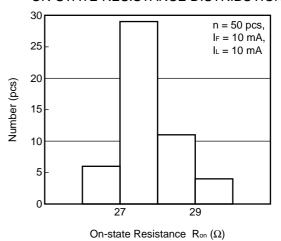


Applied Voltage $V_D(V)$ Load Voltage $V_L(V)$

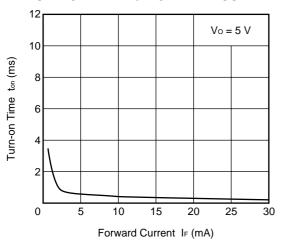
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERTURE



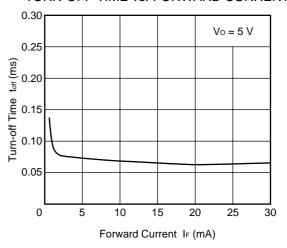
ON-STATE RESISTANCE DISTRIBUTION



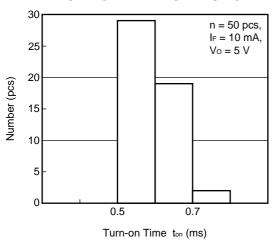
TURN-ON TIME vs. FORWARD CURRENT



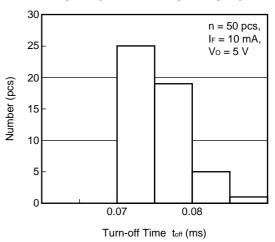
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

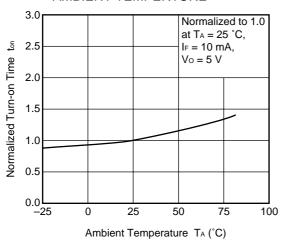


TURN-OFF TIME DISTRIBUTION

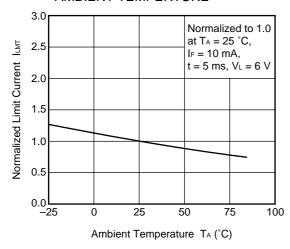


Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERTURE

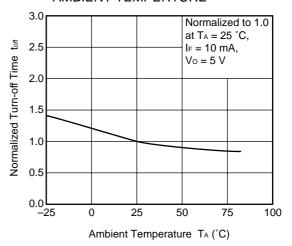


NORMALIZED LIMIT CURRENT vs. AMBIENT TEMPERTURE

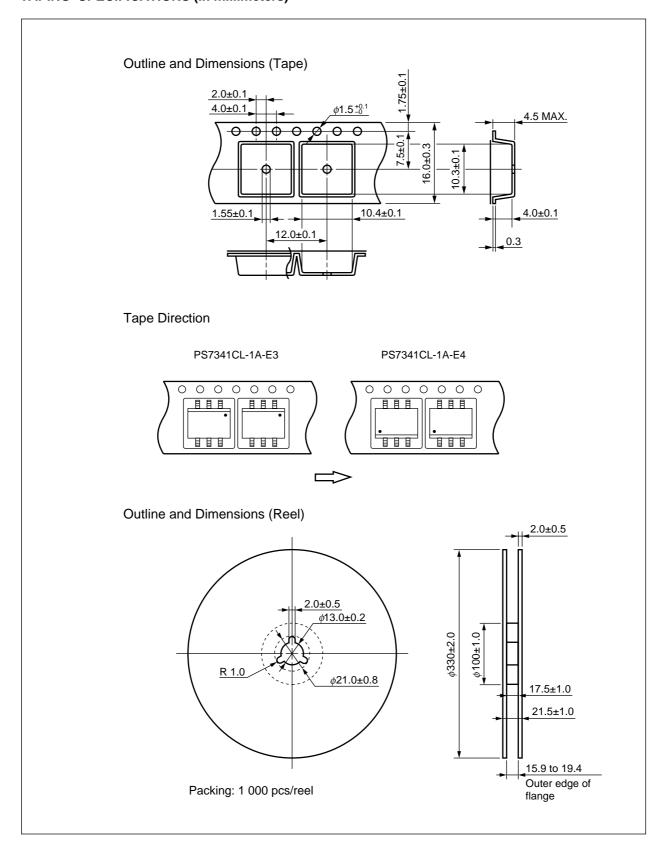


Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERTURE



TAPING SPECIFICATIONS (in millimeters)



RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

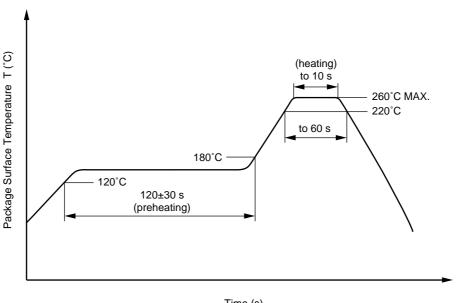
Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Two

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

Preheating conditions 120°C or below (package surface temperature)

• Number of times One

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

Peak temperature (lead part temperature) 350°C or below
 Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- <R>
- To avoid quality degradation, assembling within 1 month after take this device out from covered pack is required. (Storage conditions 25°C, 65%RH MAX.)
- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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